

PC4H510NIP

Mini Flat Half-pitch Type High Collector-Emitter Voltage Photocoupler

■ Features

1. High collector-emitter voltage
Collector-emitter voltage:350V
2. Compact and thin package Half pitch, mini flat package
3. Recognized by UL, file No. E64380

■ Applications

1. Modems

■ Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	*1 Forward current	I_F	50	mA
	*2 Peak forward current	I_{FM}	1	A
	Reverse voltage	V_R	6	V
Output	*1 Power dissipation	P	70	mW
	Collector-emitter voltage	V_{CEO}	350	V
	Emitter-collector voltage	V_{ECO}	6	V
	Collector current	I_C	50	mA
	*1 Collector power dissipation	P_C	150	mW
	*1 Total power dissipation	P_{tot}	170	mW
	Operating temperature	T_{opr}	-25 to +100	°C
	Storage temperature	T_{stg}	-55 to +125	°C
	*3 Isolation voltage	$V_{iso} (rms)$	2.5	kV
	*4 Soldering temperature	T_{sol}	260	°C

*1 The derating factors of absolute maximum ratings due to ambient temperature are shown in Fig.2 to 5

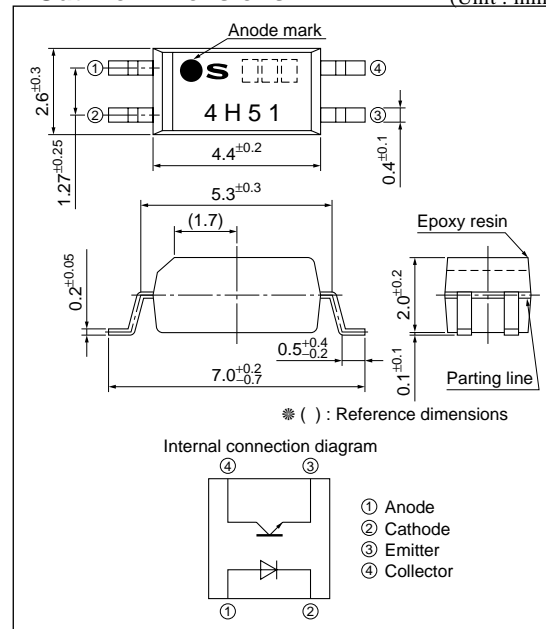
*2 Pulse width $\leq 100\mu s$, Duty ratio=0.001 (shown in Fig.6)

*3 40 to 60% RH, AC for 1 min, f=60Hz

*4 For 10 s

■ Outline Dimensions

(Unit : mm)



■ Electro-optical Characteristics

(Ta=25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	V_F	$I_F=20\text{mA}$	—	1.2	1.4	V
	Reverse current	I_R	$V_R=4\text{V}$	—	—	10	μA
	Terminal capacitance	C_t	$V=0, f=1\text{kHz}$	—	30	250	pF
Output	Collector dark current	I_{CE0}	$V_{CE}=200\text{V}, I_F=0$	—	—	1	μA
	Collector-emitter breakdown voltage	BV_{CEO}	$I_C=0.1\text{mA}, I_F=0$	350	—	—	V
	Emitter-collector breakdown voltage	BV_{ECO}	$I_E=10\mu\text{A}, I_F=0$	6	—	—	V
Transfer characteristics	Collector current	I_C	$I_F=5\text{mA}, V_{CE}=5\text{V}$	2.0	4.0	12.0	mA
	Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_F=20\text{mA}, I_C=1\text{mA}$	—	0.1	0.3	V
	Isolation resistance	R_{ISO}	DC500V, 40 to 60%RH	5×10^{10}	10^{11}	—	Ω
	Floating capacitance	C_f	$V=0, f=1\text{MHz}$	—	0.6	1.0	pF
	Cut-off frequency	f_c	$V_{CE}=5\text{V}, I_C=2\text{mA}, R_L=100\Omega, -3\text{dB}$	—	50	—	kHz
	Response time	Rise time	$V_{CE}=2\text{V}$ $I_C=2\text{mA}$ $R_L=100\Omega$	—	4	10	μs
		Fall time		—	5	12	μs

Fig.1 Forward Current vs. Ambient Temperature

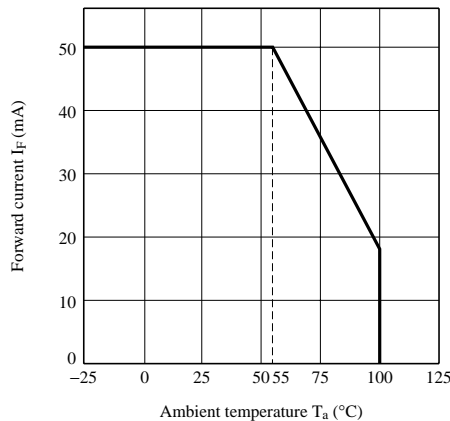


Fig.2 Diode Power Dissipation vs. Ambient Temperature

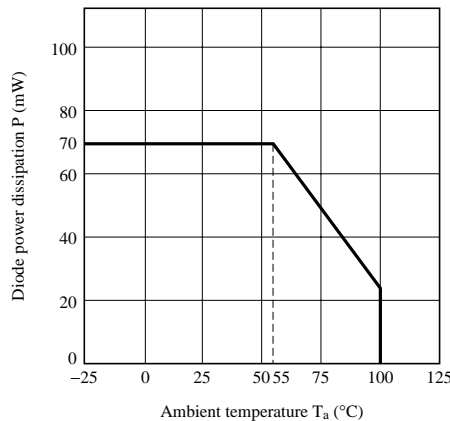


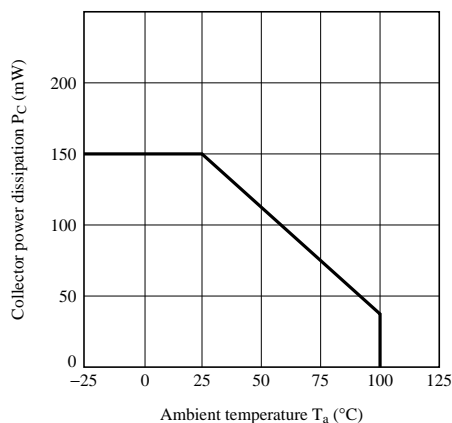
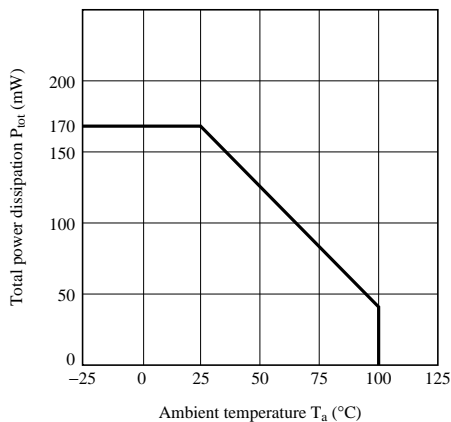
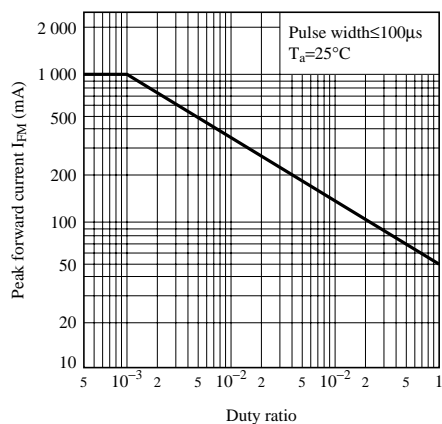
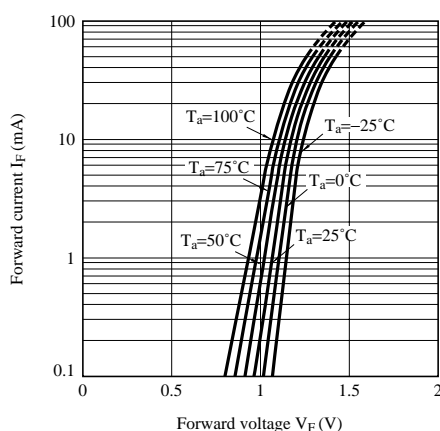
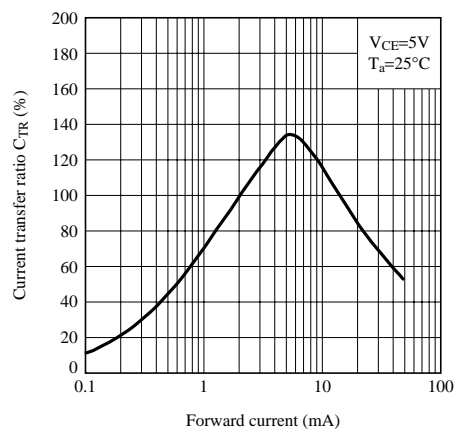
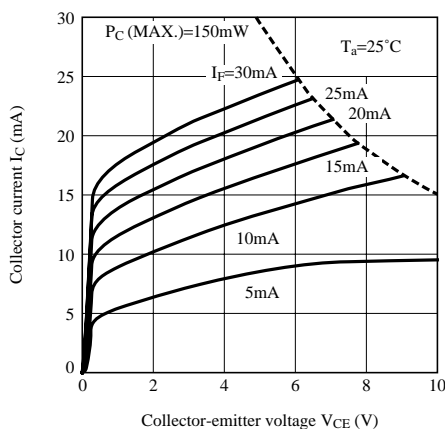
Fig.3 Collector Power Dissipation vs. Ambient Temperature**Fig.4 Total Power Dissipation vs. Ambient Temperature****Fig.5 Peak Forward Current vs. Duty Ratio****Fig.6 Forward Current vs. Forward Voltage****Fig.7 Current Transfer Ratio vs. Forward Current****Fig.8 Collector Current vs. Collector-emitter Voltage**

Fig.9 Relative Current Transfer Ratio vs. Ambient Temperature

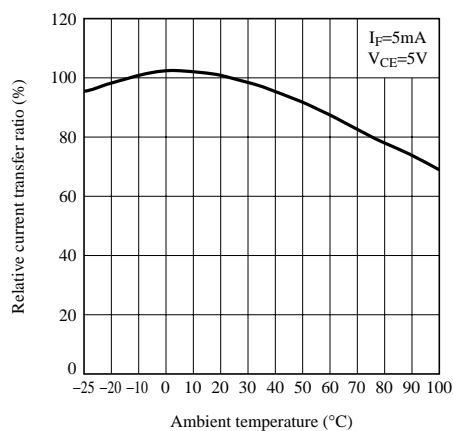


Fig.10 Collector-emitter Saturation Voltage vs. Ambient Temperature

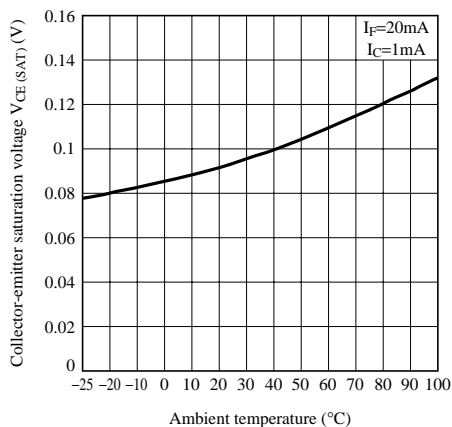


Fig.11 Collector Dark Current vs. Ambient Temperature

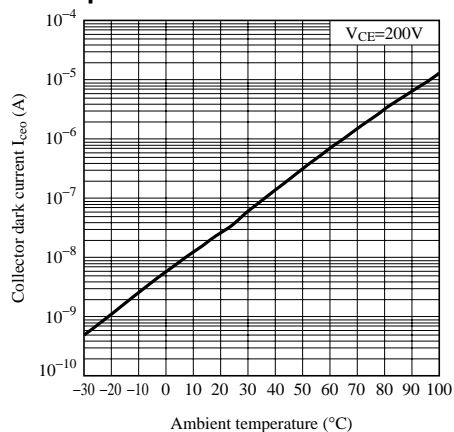


Fig.12 Response Time vs. Load Resistance

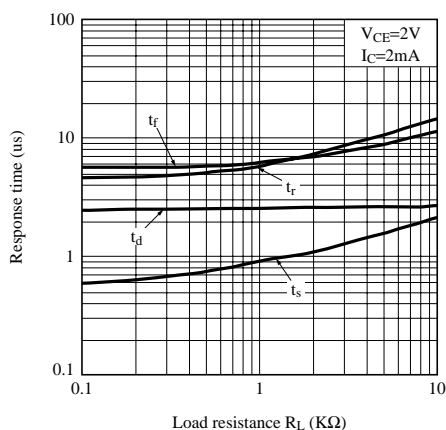


Fig.13 Test Circuit for Response Time

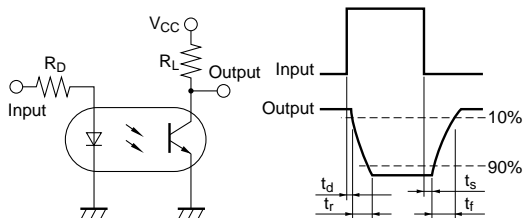


Fig.14 Collector-emitter Saturation Voltage vs. Forward Current

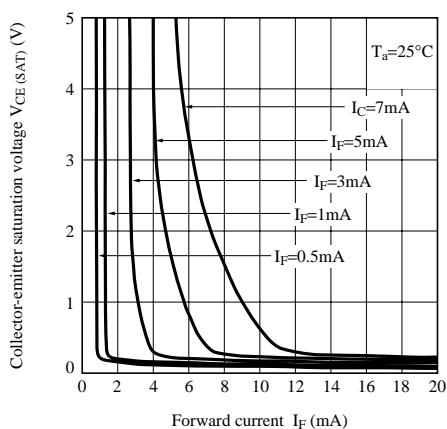
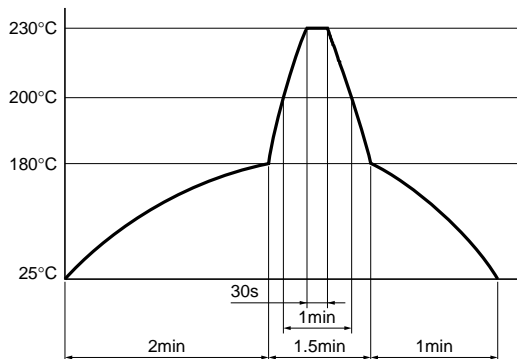


Fig.15 Reflow Soldering

Only one time soldering is recommended within the temperature profile shown below.



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